Mounting Pad Dimensions for Renesas Optocouplers & Solid State Relays

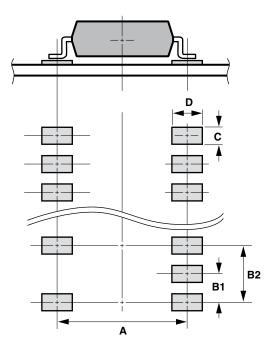
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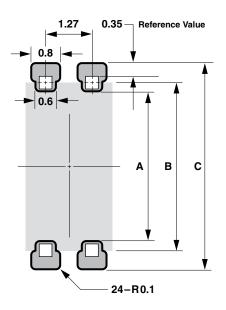
Package	А	B1	B2	С	D		
Surface Mount DIP, SOP and SSOP Packages (mm)							
DIP (SMT) 4, 6, 8, 12, 16 Pin	8.2	-	2.54	1.7	2.2		
DIP (L2 – SMT) 4, 6, 8, 16 Pin	10.2	-	2.54	1.7	2.2		
SOP 4, 8, 16 Pin	6.25	-	2.54	0.8	1.45		
SOP 5 Pin	6.25	1.27	2.54	0.8	1.45		
SSOP 4, 16 Pin 1.27mm Pitch	6.25	-	1.27	0.8	1.45		
SSOP 8 Pin (SO-8) 1.27mm Pitch	5.25	-	1.27	0.8	1.45		
SSOP 12 Pin 0.8mm Pitch	6.25	-	0.8	0.5	1.45		
LSDIP 8 Pin	16.6	-	1.27	0.9	2		
SDIP 6 Pin	9.2	-	1.27	0.8	2.2		

Package	А	В	С			
Mini Flat Packages (mm)						
Optocoupler Version PS29xx, 1.27mm Pitch	4.14	4.7	5.7			
SSR Version PS78xx, 1.27mm Pitch	3.6	4.4	5.3			

NOTES: The Mini Flat package meets the 4.0mm air distance and outer creepage requirement.

All dimensions are subject to change without notice. Please contact CEL to ensure that you have the latest version of this document.





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